ABSTRACT

SINGLE WAFER TYPE SUBSTRATE CLEANING METHOD AND APPARATUS

A single wafer type wet-cleaning apparatus for effectively preventing chemical fluids from flowing to the back face of a wafer when the back face thereof is wet-cleaned by chemical fluids, wherein purified water is injected and supplied to the back face of the wafer while a plurality of chemical fluids is sequentially supplied vertically from above to the wafer, which is rotatably supported, so that the purified water cleans the back face of the wafer and effectively prevents the chemical fluids from flowing to the back face of the wafer.

Fig. 1